

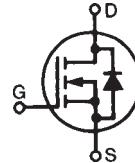
High Voltage Power MOSFET

IXTH 6N120
IXTT 6N120

V_{DSS} = 1200 V
I_{D25} = 6 A
R_{DS(on)} = 2.6 Ω

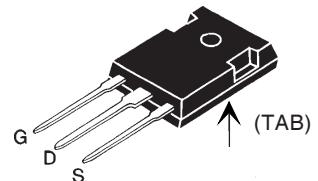
N-Channel Enhancement Mode
Avalanche Rated

Preliminary Data Sheet

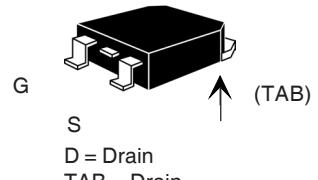


Symbol	Test Conditions	Maximum Ratings		
V _{DSS}	T _J = 25°C to 150°C	1200		V
V _{DGR}	T _J = 25°C to 150°C; R _{GS} = 1 MΩ	1200		V
V _{GS}	Continuous	±20		V
V _{GSM}	Transient	±30		V
I _{D25}	T _C = 25°C	6		A
I _{DM}	T _C = 25°C, pulse width limited by T _{JM}	24		A
I _{AR}	T _C = 25°C	6		A
E _{AR}	T _C = 25°C	25		mJ
E _{AS}	T _C = 25°C	500		mJ
dv/dt	I _S ≤ I _{DM} , di/dt ≤ 100 A/μs, V _{DD} ≤ V _{DSS} , T _J ≤ 150°C, R _G = 2 Ω	5		V/ns
P _D	T _C = 25°C	300		W
T _J		-55 ... +150		°C
T _{JM}		150		°C
T _{stg}		-55 ... +150		°C
T _L	1.6 mm (0.062 in.) from case for 10 s	300		°C
M _d	Mounting torque	1.13/10	Nm/lb.in.	
Weight	TO-247 AD TO-268	6 4		g g

TO-247 AD (IXTH)



TO-268 (IXTT) Case Style



G = Gate
S = Source

D = Drain
TAB = Drain

Features

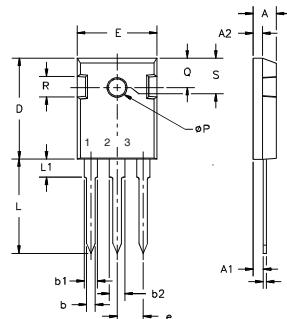
- International standard packages
- Low R_{DS(on)} HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect

Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions (T _J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
V _{DSS}	V _{GS} = 0 V, I _D = 250 μA	1200		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.5		5.0 V
I _{GSS}	V _{GS} = ±20 V _{DC} , V _{DS} = 0		±100	nA
I _{DSS}	V _{DS} = V _{DSS} V _{GS} = 0 V	T _J = 25°C T _J = 125°C	25 500	μA
R _{DS(on)}	V _{GS} = 10 V, I _D = 0.5 I _{D25} Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %		2.6	Ω

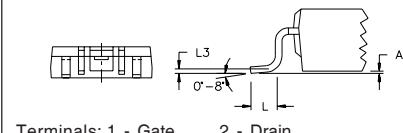
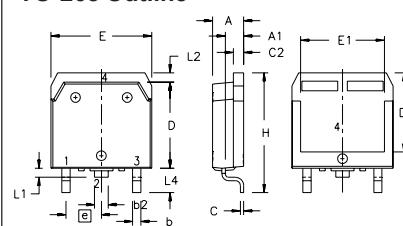
Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	Min.	Typ.	Max.
g_{fs}	$V_{DS} = 20 \text{ V}; I_D = 0.5 I_{D25}$, pulse test	3	5	S	
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	1950		pF	
		175		pF	
		60		pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 4.7 \Omega$ (External)	28		ns	
		33		ns	
		42		ns	
		18		ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$	56		nC	
		13		nC	
		25		nC	
R_{thJC}			0.42	K/W	
R_{thCK}	(TO-247)		0.21	K/W	

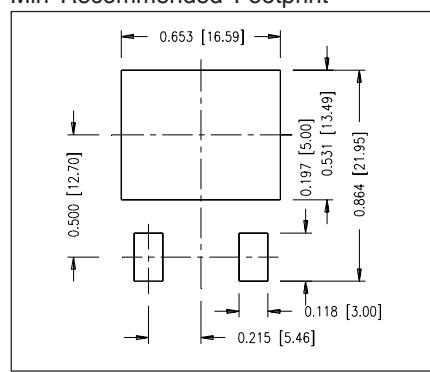
TO-247 AD Outline

Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	.205	.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	.232	.252
R	4.32	5.49	.170	.216
S	6.15	BSC	242	BSC

Source-Drain Diode
Characteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test Conditions	min.	typ.	max.
I_s	$V_{GS} = 0 \text{ V}$		6	A
I_{SM}	Repetitive		24	A
V_{SD}	$I_F = I_s, V_{GS} = 0 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$		1.5	V
T_{rr}	$I_F = 6 \text{ A}$ $-di/dt = 100 \text{ A}/\mu\text{s}$	850		ns

TO-268 Outline

Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

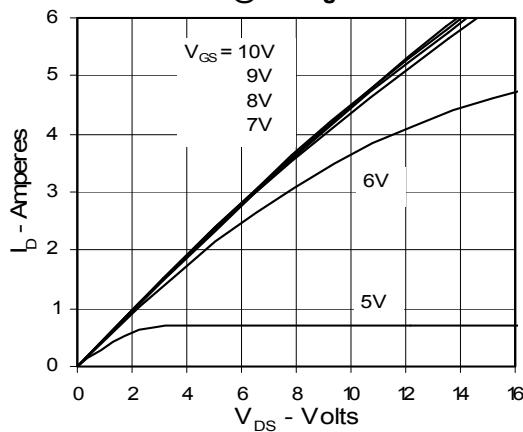
Min Recommended Footprint


IXYS reserves the right to change limits, test conditions, and dimensions.

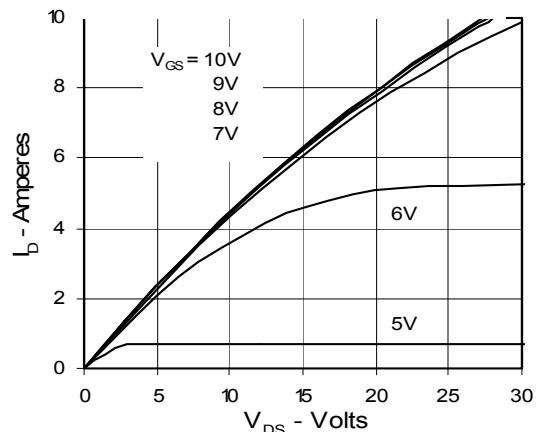
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343

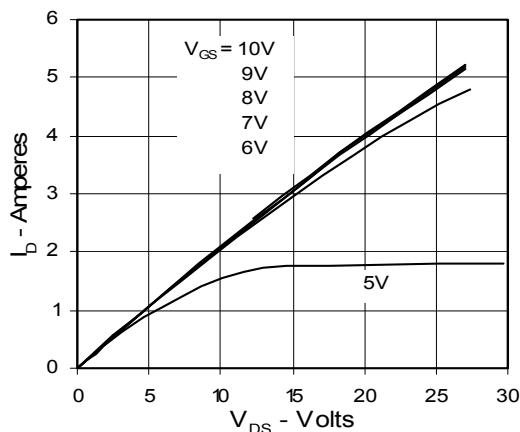
**Fig. 1. Output Characteristics
@ 25 Deg. C**



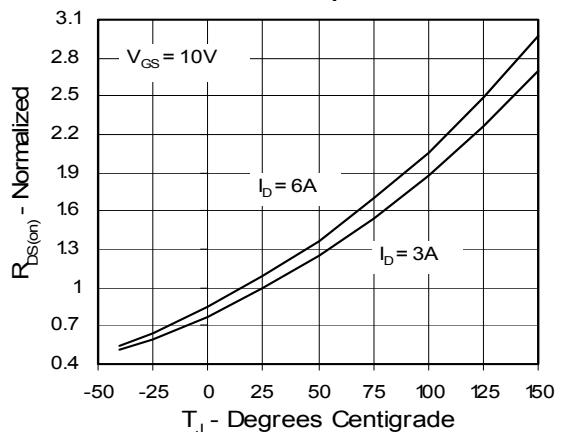
**Fig. 2. Extended Output Characteristics
@ 25 deg. C**



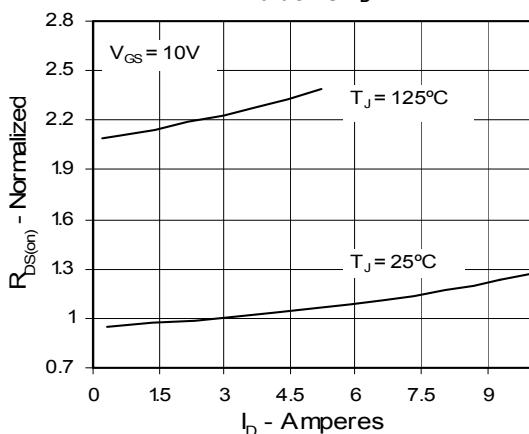
**Fig. 3. Output Characteristics
@ 125 Deg. C**



**Fig. 4. $R_{DS(on)}$ Normalized to I_{D25} Value vs.
Junction Temperature**



**Fig. 5. $R_{DS(on)}$ Normalized to I_{D25}
Value vs. I_D**



**Fig. 6. Drain Current vs. Case
Temperature**

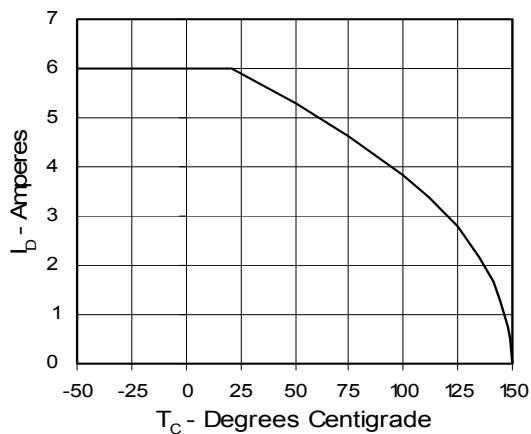
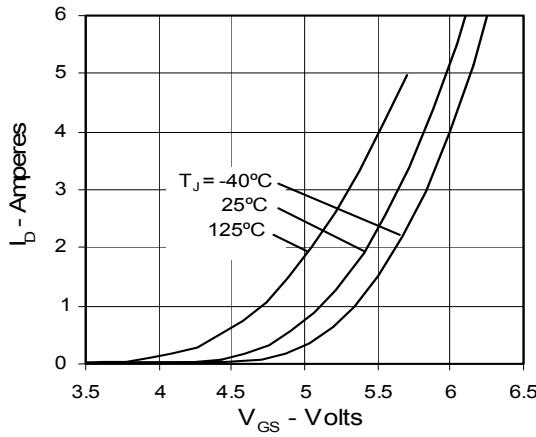
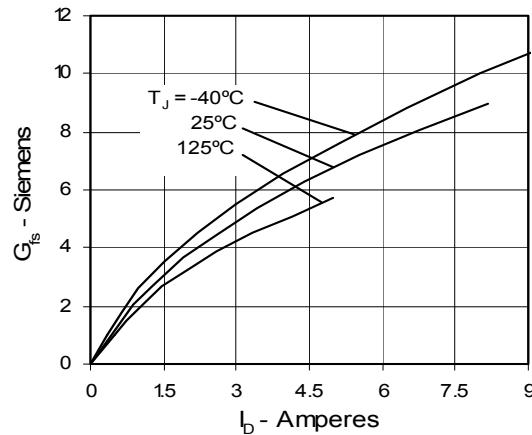
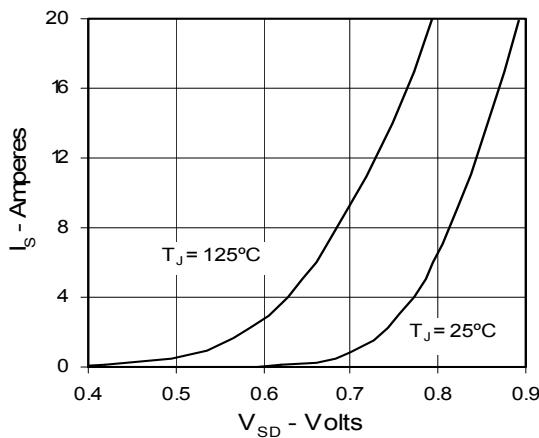
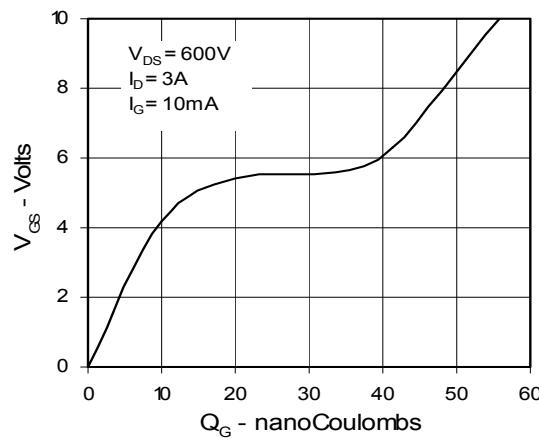
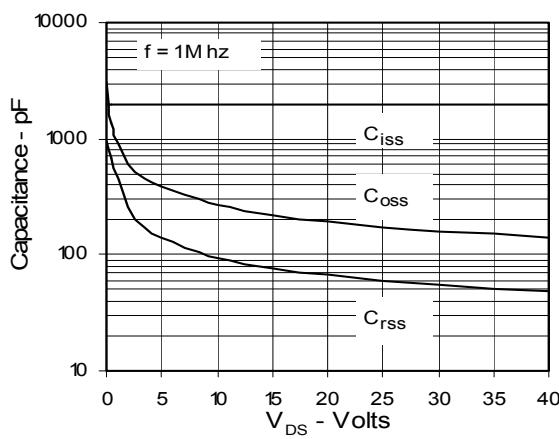
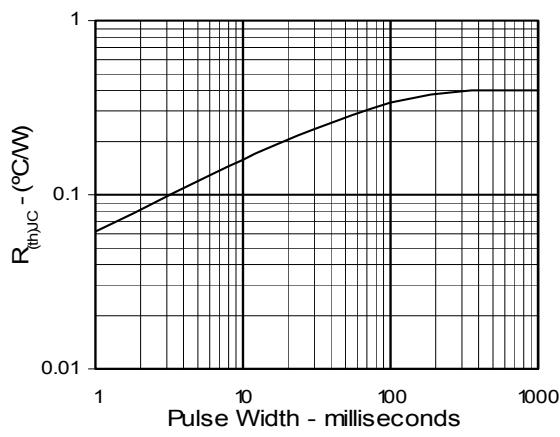


Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Source Current vs. Source-To-Drain Voltage

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Maximum Transient Thermal Resistance


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